

OPTICAL EPOXY RESINS, GLOB TOP, STRUCTURAL BONDING - ONE-COMPONENT*

REF	CURONG SCHEDULE Recommended	POT LIFE	VISCOSITY	Tg	DEGRADATION	FILLER	THERMAL EXPANSION		RESISTIVITY	COMMENTS
							BEFORE TG	AFTER TG		
E506	1 min at 125°C	3 days at 4°C	0,4 Pa.S	80-90°C	350-360°C		60-70.10 ⁻⁶ /°C	140-160.10 ⁻⁶ /°C	10 ¹³ Ω.cm	Chip protection smart cards - high purity
E506-5	1 h at 135°C	1 month at 20°C	12 Pa.S	120-135°C	370-390°C		60-80.10 ⁻⁶ /°C	170-190.10 ⁻⁶ /°C	10 ¹⁷ Ω.cm	Silicon chip protection - Black -High purity
E506-7	10 min at 100°C	5 h at 20°C	4 Pa.S	60-70°C	370-390°C		55-65.10 ⁻⁶ /°C	130-160.10 ⁻⁶ /°C	10 ¹³ Ω.cm	Silicon chip protection - High purity - High resistance to humidity
E507-3	5 min at 150°C	24 h at 25°C	22,5 Pa.S	160-170°C	350-370°C	72%	15-25.10 ⁻⁶ /°C	55-65.10 ⁻⁶ /°C	10 ¹³ Ω.cm	Chip protection smart cards
E508	5 min at 150°C	6 days at 20°C	70 Pa.S	145-155°C	> 350°C	75%	18-20.10 ⁻⁶ /°C	65-75.10 ⁻⁶ /°C	10 ¹³ Ω.cm	Chip protection smart cards - Recommended for large size chips
E508HV	5 min at 150°C	5 days at 20°C	130 Pa.S	145-155°C	> 350°C		23-25.10 ⁻⁶ /°C	85-100.10 ⁻⁶ /°C	10 ¹³ Ω.cm	Chip protection smart cards - Used to form a cordon of resin around the chip (dam)
E517	30 min at 150°C	1 month at 20°C	50 Pa.S	70-100°C	330-350°C		25-30.10 ⁻⁶ /°C	55-65.10 ⁻⁶ /°C	10 ¹³ Ω.cm	Silicon chip bonding and protection - High purity - Good thermal conductivity
E518FC	1 min at 150°C	8 h at 25°C	3,5 Pa.S	40-60°C	350-370°C	59%	30-40.10 ⁻⁶ /°C	100-110.10 ⁻⁶ /°C	10 ¹³ Ω.cm	Semiconductors protection Flip-chip technology
E519FC	1 min at 150°C	8 h at 25°C	3,5 Pa.S	40-60°C	350-370°C	64%	35-50.10 ⁻⁶ /°C	110-120.10 ⁻⁶ /°C	10 ¹³ Ω.cm	Semiconductors protection Flip-chip technology - UL94VO
NEA155	10 min at 150°C	4 months at 25°C	42 Pa.S	50-60°C	360-380°C	6%	90-100.10 ⁻⁶ /°C	180-200.10 ⁻⁶ /°C	10 ¹⁵ Ω.cm	Medium/high viscosity thixotropic paste for SMD - Red colour

The information in this sheet is based on data measurements which we believe to be correct. Epotecny, however, does not accept responsibility for the adaptation of this product to any particular use.

* for more precision on the technical properties, to refer to the individual data sheet.

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épotecny

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